



Economic & Smart Printer

Scale up – PCB 550mm x 510mm

E2

The model E2 from US-2000X & 2000XQ is designed for a high performance of quality and a scaled-up capacity ESE best cost-effective model with much more enhanced standard features integrated

Much stable solid frame & Table structure for a cost-saving and 3 stages conveyor system for high throughput

Technological Cleaning system – Easy & Fast Convertible cleaning system for Paper and Paperless

*Wipe roll paper cleaning or Paperless cleaning can be applied together

Standard E2 Wet print accuracy is 25 microns @ 6 sigma, Cpk ≥ 2 by 3rd party measurement system

A high-level **E2+** of standard E2 with 20 microns @ 6 sigma can be delivered for much precise printing performance

Enhanced standard Features

- * 2D inspection for solder excess, less, short and position error
- * SPI closed loop with Kohyong, Pami, TRI, Pemtron, Cyberoptics
- * Production programming by network
- * Auto stencil loading & positioning
- * Auto camera calibration
- * Auto Alignment before production
- * Auto stencil inspection & cleaning for a containment area
- * Auto Squeegee center position calibration
- * Auto Alignment accuracy measuring for table & camera
- * ESE standard MES data
- * Program for Auto PCB support tooling for Gridlock, Quik-Tool
- * PCB barcode traceability by vision camera



2D inspection
Less, Excess, Bridge, Position



SPI close loop



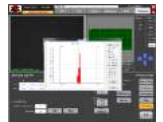
Program by network



Auto Camera calibration



Auto Stencil Inspection



Auto Alignment Accuracy measuring



Auto Alignment



PCB barcode traceability



ESE standard MES data



Hybrid Cleaning system :
Easy convertible cleaning mode to
Standard paper cleaning or Paperless cleaning

PCB size	50mm x 50mm - 550mm x 510mm
PCB Thickness	0.3mm to 6mm
Stencil size	550mm, 584mm, 650mm, 736mm
Cycle time	10sec / under optimized condition
Alignment accuracy	±12.5 um @ 6 sigma
Printing repeatability	±25 um @ 6 sigma , Cpk ≥2.0 [**E2+ : ±20 um @ 6 sigma , Cpk ≥2.0]



Much Flexible Printer

Scale up – PCB 700mm x 610mm

E7

The model E7 from US-7000X is designed for a flexible printing capacity of PCB 700mm by 610mm based on E2's stable printing repeatability

With enhanced standard features integrated on E2, standard 3 stages conveyor system for high throughput and a high printing performance - alignment repeatability is ± 12.5 microns @ 6 sigma, $Cpk \geq 2$ by 3rd party measurement tooling and Wet print accuracy is 25 microns @ 6 sigma, $Cpk \geq 2$

Retrofit Options

To improve productivity, a retrofit option applicable

Touch screen monitor (22")

Inside Temperature & Humidity display

Auto solder paste dispenser[JAR or Tube type]

Solder paste roll height check system

Automatic Support Pin placemnt

Glue Dispenser

Programmable Y (Side) Clamp pressure

Easy clip Squeegee system (one-touch)

Barcode Management (*RFID management available)

Side vacuum clamp tool

Side lifter for PCB edge support

Real Squeegee pressure closed loop

Real time squeegee pressure closed loop

Ionizer(Anti-Static) PCB cleaning

Air conditioner

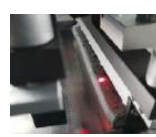
Temperature controller

Center Table vacuum pressure sensor

Area sensor for safety [Door both side]



Auto solder paste dispenser (JAR, Syringe)



Solder roll height check



Glue dispenser



Auto support pin placement



Barcode management (RFID management workable)



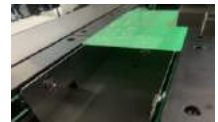
Inside temperature & humidity display



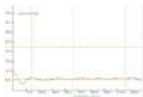
Programmable Y (side) clamp pressure



Side vacuum clamp



Side lifter for PCB edge support



*Real squeegee pressure closed loop
*Real time squeegee pressure closed loop



Area sensor for safe [Door both side]



Customizing Vacuum nest

Additional optional item request, please contact ESE

PCB size	50mm x 50mm - 700mm x 610mm
PCB Thickness	0.3mm to 6mm
Stencil size	650mm, 736mm, 800mm, 850mm, 900mm
Cycle time	12sec / under optimized condition
Alignment accuracy	± 12.5 um @ 6 sigma
Printing repeatability	± 25 um @ 6 sigma , $Cpk \geq 2.0$



**Ultimate speed & Smart performance
Back-to-Back Printer**

Integrated shuttle on conveyor

Single printer or Back-to-Back configured line



Ultimate cycle time [core 5sec] and Qualified printing quality & repeatability printer [20um@6sigma] for single or back-to-back configurable printer

Much high productivity for single products – Top & Bottom printing together on each lane

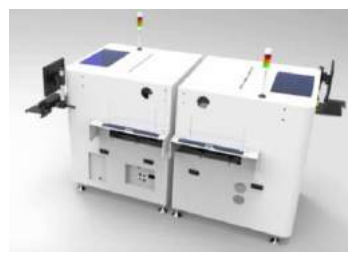
Much flexible production for each different product for much faster productivity

All advanced & enhanced standard features of E2 & E7 applicable

Linear motor applied for stable & fast camera and 3 stages conveyor system as standard

Optional output conveyor integrated shuttle system for Back to Back line

Input conveyor shuttle applicable as Optional



Enhanced standard Features

- * 2D inspection for solder excess, less, short and position error
- * SPI closed loop with Kohyong, Pami, TRI, Pemtron, Cyberoptics
- * Production programming by network
- * Auto stencil loading & positioning
- * Auto camera calibration
- * Auto Alignment before production
- * Auto stencil inspection & cleaning for a containment area
- * Auto Squeegee center position calibration
- * Auto Alignment accuracy measuring for table & camera
- * ESE standard MES data
- * Program for Auto PCB support tooling for Gridlock, Quik-Tool
- * PCB barcode traceability by vision camera



2D inspection
Less, Excess, Bridge, Position



SPI close loop



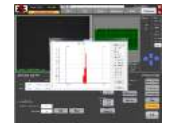
Program by network



Auto Camera calibration



Auto Stencil Inspection



Auto Alignment Accuracy measuring



Auto Alignment



PCB barcode traceability



ESE standard MES data



Hybrid Cleaning system :
Easy convertible cleaning mode to
Standard paper cleaning or Paperless cleaning

PCB size	50mm x 50mm - 350mm x 250mm [* Optional 380mm x 280mm]
PCB Thickness	0.3mm to 6mm
Stencil size	550mm, 584mm (23"), 650mm
Core Cycle time	5sec / under optimized condition
Alignment accuracy	±12.5 um @ 6 sigma
Printing repeatability	±25 um @ 6 sigma , Cpk ≥2.0

Super cycle time and High productivity

H2

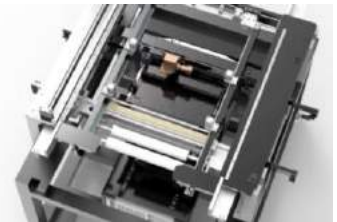
H2 realizes super cycle time based on ESE own technology
 [core cycle time – 5.5~6 sec and including cleaning – 10sec under ESE optimized condition]

The most stable mechanical structure and printing performance with machine alignment 10microns and repeatability 20microns will make you cut down sharply your production time and much higher productivity

Technological Cleaning system – Easy & Fast Convertible cleaning system for Paper and Paperles

Linear motor applied for stable & fast camera and 3 stages conveyor system as standard

Back-to-Back configurable modification available for medium size PCB production



Retrofit Options

To improve productivity, Below retrofit options are recommended

Touch screen monitor (22")

Inside Temperature & Humidity display

Auto solder paste dispenser[JAR or Tube type]

Solder paste roll height check system

Programmable Y (Side) Clamp pressure with Y clamp

Easy clip Squeegee system (one-touch)

Barcode Management (*RFID management available)

Side lifter for PCB edge support

Real Squeegee pressure closed loop

Real time squeegee pressure closed loop

Ionizer(Anti-Static) PCB cleaning

Air conditioner

Temperature controller

Center Table vacuum pressure sensor

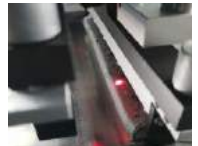
Area sensor for safe [Door both side]



Auto solder paste dispenser (JAR, Syringe)



Solder roll height check



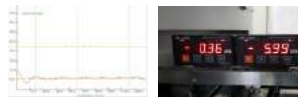
Programmable Y (side) clamp pressure



Side lifter for PCB edge support



Inside temperature & humidity display



*Real squeegee pressure closed loop
 *Real time squeegee pressure closed loop



Area sensor for safe [Door both side]



Barcode management (RFID management workable)

Additional optional item request, please contact ESE

PCB size	50mm x 50mm - 550mm x 510mm
PCB Thickness	0.3mm to 6mm
Stencil size	550mm, 584mm (23"), 650mm, 736mm(29")
Core Cycle time	6sec / under optimized condition
Alignment accuracy	±12.5 um @ 6 sigma
Printing repeatability	±25 um @ 6 sigma , Cpk ≥2.0



Qualified professional large Printer

PCB up to 850mm

E8

The automatic stencil printing system E8 based on Standard E2 & E7 platform was developed to cover LED, LCD and much larger substrate up to 850mm.

As a qualified professional large printer by a leading LED, LCD customers, E8 includes all standard E2 & E7 printer features & function and most flexible system in this industry field.

Up to 10kgs* substrate weight on E8 can be handled and flexible design allows customer mask stencil size loading including ESE standard configuration (Optional)

Including Standard clamping system, special designed side vacuum clamp tool kit supports much perfect board clamping and printing result from a warpage

Enhanced standard Features

- * 2D inspection for solder excess, less, short and position error
- * SPI closed loop with Kohyong, Pami, TRI, Pemtron, Cyberoptics
- * Production programming by network
- * Auto stencil loading & positioning
- * Auto camera calibration
- * Auto Alignment before production
- * Auto stencil inspection & cleaning for a containment area
- * Auto Squeegee center position calibration
- * Auto Alignment accuracy measuring for table & camera
- * ESE standard MES data
- * Program for Auto PCB support tooling for Gridlock, Quik-Tool
- * PCB barcode traceability by vision camera



2D inspection
Less, Excess, Bridge, Position



SPI close loop



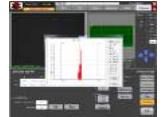
Program by network



Auto Camera calibration



Auto Stencil Inspection



Auto Alignment
Accuracy measuring



Auto Alignment



PCB barcode traceability



ESE standard MES data

PCB size	70mm x 70mm - 850mm x 610mm
PCB Thickness	0.3mm to 6mm
Stencil size	736mm(29"), 800mm, 850mm, 980mm, 1050mm x 850mm
Cycle time	17sec
Alignment accuracy	±12.5 um @ 3 sigma
Printing repeatability	±25 um @ 3 sigma , Cpk ≥1.33



Qualified professional large Printer

**PCB up to 1000mm
X direction Printing & Cleaning**

LX1

The automatic stencil printing system L1 based on Standard E8 platform was developed to cover LED, LCD and much larger substrate up to 1000mm.

As a qualified professional large printer by a leading LED, LCD customers, L1 includes all standard E8 printer features & function and most flexible system in this industry field.

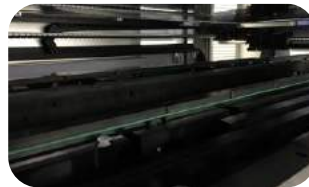
Up to 10kgs* substrate weight on E8 can be handled and flexible design allows customer mask stencil size loading including ESE standard configuration (Optional)

Including Standard clamping system, special designed side vacuum clamp tool kit supports much perfect board clamping and printing result from a warpage

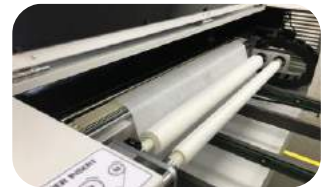
Effective X direction printing & cleaning direction applied

Enhanced standard Features

- * 2D inspection for solder excess, less, short and position error
- * SPI closed loop with Kohyong, Parmi, TRI, Pemtron, Cyberoptics
- * Production programming by network
- * Auto camera calibration
- * Auto Alignment before production to reduce human error and production time
- * Auto stencil inspection & cleaning for a containment area
- * Auto Squeegee calibration for new squeegee, blade change and squeegee center position before production
- * Auto Alignment accuracy measuring for printer table & camera accuracy
- * ESE standard MES data
- * Program for Auto PCB support tooling for Gridlock, Quik-Tool, GemiXlock
- * Production data collect
- * PCB barcode traceability by vision camera
- * Side vacuum clamp kit



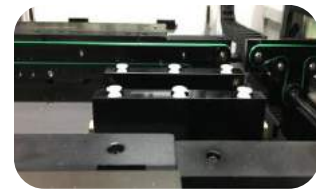
Standard 3 stages conveyor system



Standard X direction cleaning system



Standard X direction printing system



Standard side vacuum clamp

PCB size	100mm x 80mm - 1000mm x 650mm
PCB Thickness	0.3mm to 6mm
Stencil size	736mm(29"), 980mm, 1300mm x 800mm
Cycle time	35sec / 1000mm PCB
Alignment accuracy	±12.5 um @ 3 sigma
Printing repeatability	±25 um @ 3 sigma , Cpk ≥1.33



Qualified professional large Printer

**PCB up to 1300mm
X direction printing & cleaning**

LX3

The automatic stencil printing system L3 based on Standard E8 platform was developed to cover LED, LCD and much larger substrate up to 1300mm.

As a qualified professional large printer by a leading LED, LCD customers, L3 includes all standard E8 printer features & function and most flexible system in this industry field.

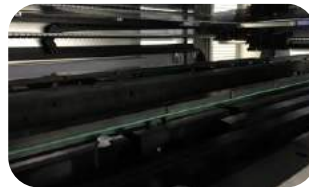
Up to 10kgs* substrate weight on E8 can be handled and flexible design allows customer mask stencil size loading including ESE standard configuration (Optional)

Including Standard clamping system, special designed side vacuum clamp tool kit supports much perfect board clamping and printing result from a warpage

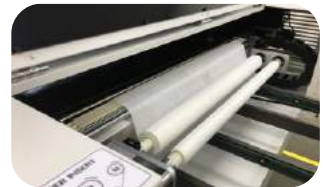
Effective X direction printing & cleaning direction applied

Enhanced standard Features

- * 2D inspection for solder excess, less, short and position error
- * SPI closed loop with Kohyong, Parmi, TRI, Pemtron, Cyberoptics
- * Production programming by network
- * Auto camera calibration
- * Auto Alignment before production to reduce human error and production time
- * Auto stencil inspection & cleaning for a containment area
- * Auto Squeegee calibration for new squeegee, blade change and squeegee center position before production
- * Auto Alignment accuracy measuring for printer table & camera accuracy
- * ESE standard MES data
- * Program for Auto PCB support tooling for Gridlock, Quik-Tool, GemiXlock
- * Production data collect
- * PCB barcode traceability by vision camera
- * Side vacuum clamp kit



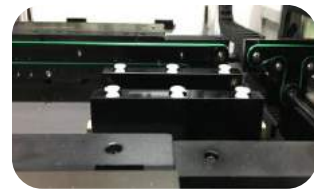
Standard 3 stages conveyor system



Standard X direction cleaning system



Standard X direction printing system



Standard side vacuum clamp

PCB size	100mm x 80mm - 1300mm x 650mm
PCB Thickness	0.3mm to 6mm
Stencil size	736mm(29"), 980mm, 1500mm x 800mm
Cycle time	40sec / 1000mm PCB
Alignment accuracy	±12.5 um @ 3 sigma
Printing repeatability	±25 um @ 3 sigma , Cpk ≥1.33



**Qualified professional
Super large Printer**

**PCB up to 1500mm
X direction printing & cleaning**

LX5

The automatic stencil printing system L5 based on Standard E8 platform was developed to cover LED, LCD and much larger substrate up to 1300mm.

As a qualified professional large printer by a leading LED, LCD customers, L5 includes all standard E8 printer features & function and most flexible system in this industry field.

Up to 10kgs* substrate weight on E8 can be handled and flexible design allows customer mask stencil size loading including ESE standard configuration (Optional)

Including Standard clamping system, special designed side vacuum clamp tool kit supports much perfect board clamping and printing result from a warpage

Effective X direction printing & cleaning direction applied

Enhanced standard Features

- * 2D inspection for solder excess, less, short and position error
- * SPI closed loop with Kohyong, Parmi, TRI, Pemtron, Cyberoptics
- * Production programming by network
- * Auto camera calibration
- * Auto Alignment before production to reduce human error and production time
- * Auto stencil inspection & cleaning for a containment area
- * Auto Squeegee calibration for new squeegee, blade change and squeegee center position before production
- * Auto Alignment accuracy measuring for printer table & camera accuracy
- * ESE standard MES data
- * Program for Auto PCB support tooling for Gridlock, Quik-Tool, GemiXlock
- * Production data collect
- * PCB barcode traceability by vision camera
- * Side vacuum clamp kit



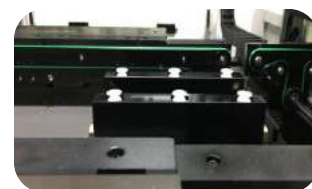
Standard 3 stages conveyor system



Standard X direction cleaning system



Standard X direction printing system



Standard side vacuum clamp

PCB size	100mm x 80mm - 1500mm x 650mm
PCB Thickness	0.3mm to 6mm
Stencil size	736mm(29"), 980mm, 1800mm x 800mm
Cycle time	45sec / 1000mm PCB
Alignment accuracy	±12.5 um @ 3 sigma
Printing repeatability	±25 um @ 3 sigma , Cpk ≥1.33

Stencil Auto Changeover Printer

FA1

FA1 is made with ESE strong R&D and the fruit of ESE's passion integrated a state of the art and advanced technology

As the leading for industry 4.0, it has been upgraded from US-2000FA and XF which had been developed by a closed cooperation between Samsung Electronics & ESE in 2012.

FA1 is the unique functional printer and should facilitate Mask stencil automatic change), fully integrated PCB support tools and hybrid cleaner(*), Auto solder paste dispenser, traceable ESE standard format of MES, SPI closed loop, software managed by barcode etc the built in various and innovated options included.

The active and advanced intelligent FA1 can realize your production line of becoming much more Smart line based on two way communication between manager and production line and it will guide much high productivity,

Maximize managing efficiency and help you to implement a real Industry 4.0 and Smart factory.

Enhanced standard Features

- * 2D inspection for solder excess, less, short and position error
- * SPI closed loop with Kohyong, Pami, TRI, Pemtron, Cyberoptics
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- * Auto camera calibration
- * Auto Alignment before production
- * Auto stencil inspection & cleaning for a containment area
- * Auto Squeegee center position calibration
- * Auto Alignment accuracy measuring for table & camera
- * ESE standard MES data
- * Program for Auto PCB support tooling for Gridlock, Quik-Tool
- * PCB barcode traceability by vision camera



Stencil mask Auto changeover(2 stencil)



Barcode management



Hybrid Cleaning system
- Paper and Paperless



PCB Auto support tooling



Auto solder paste dispenser

PCB size	50mm x 50mm - 350mm x 250mm
PCB Thickness	0.3mm to 6mm
Stencil size	584mm (23") or 736mm (29")
Cycle time	12sec (* Stencil Changeover – within 2min)
Alignment accuracy	±12.5 um @ 6sigma
Printing repeatability	±25 um @ 6 sigma , Cpk ≥2.0